

**AMENDMENTS TO THE SPECIFICATION**

Please replace the Abstract of the Disclosure with the following amended Abstract.

**ABSTRACT OF THE DISCLOSURE**

A dynamic quantity sensor includes a sensor board (10) having a movable portion (13) at one surface side thereof and a silicon layer (14) at another surface side thereof. The movable portion (13) is displaced under application of a dynamic quantity. The silicon layer (14) is separated from the movable portion (13) through an insulator (15). The dynamic quantity sensor also includes a circuit board (20) for transmitting/receiving electrical signals to/from the sensor board (20). The circuit board (20) is disposed to confront the one surface of the sensor board (10) through a gap portion (30) and cover the movable portion (13). The sensor board (20) and the circuit board (20) are bonded to each other around the gap portion (30) so that a bonding portion (40) is formed to substantially surround the gap portion (30) and thereby seal the gap portion (30).